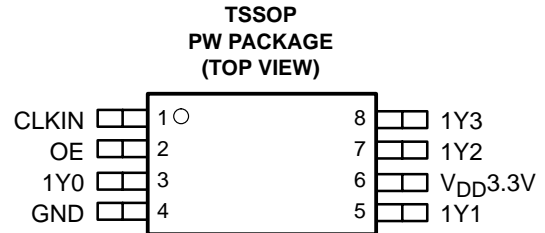


- **General-Purpose and PCI-X 1:4 Clock Buffer**
- **Operating Frequency: 0 MHz to 140 MHz**
- **Low Output Skew: <100 ps**
- **Distributes One Clock Input to One Bank of Four Outputs**
- **Output Enable Control That Drives Outputs Low When OE Is Low**
- **Operates From Single 3.3-V Supply**
- **8-Pin TSSOP Package**



description

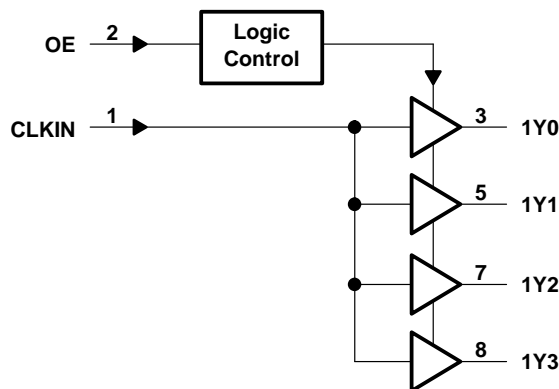
The CDCV304 is a high-performance, low-skew, general-purpose and PCI-X clock buffer. It distributes one input clock signal (CLKIN) to the output clocks (1Y[0:3]). It is specifically designed for use with PCI-X applications. The CDCV304 operates at 3.3 V.

The CDCV304 is characterized for operation from -40°C to 85°C for automotive and industrial applications.

FUNCTION TABLE

INPUTS		OUTPUT
CLKIN	OE	1Y (0:3)
L	L	L
H	L	L
L	H	L
H	H	H

functional block diagram



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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CDCV304

140-MHz PCI-X CLOCK BUFFER

SCAS643B – SEPTEMBER 2000 REVISED JULY 2002

Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
1Y[0–3]	3, 5, 7, 8	O	Buffered output clocks
CLKIN	1	I	Input reference frequency
GND	4	Power	Ground
OE	2	I	Outputs enable control
V _{DD} 3.3V	6	Power	3.3-V supply

absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage range, V _{DD}	–0.5 V to 4.3 V
Input voltage range, V _I (see Notes 1 and 2)	–0.5 V to V _{DD} + 0.5 V
Output voltage range, V _O (see Notes 1 and 2)	–0.5 V to V _{DD} + 0.5 V
Input clamp current, I _{IK} (V _I < 0 or V _I > V _{DD})	±50 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{DD})	±50 mA
Continuous total output current, I _O (V _O = 0 to V _{DD})	±50 mA
Package thermal impedance, θ _{JA} (see Note 3): PW package	230.5°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 2. This value is limited to 4.6 V maximum.
 3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V _{DD}	3	3.3	3.6	V
High-level input voltage, V _{IH}	0.7×V _{DD}			V
Low-level input voltage, V _{IL}	0.3×V _{DD}			V
Input voltage, V _I	0		V _{DD}	V
High-level output current, I _{OH}			–24	mA
Low-level output current, I _{OL}			24	mA
Operating free-air temperature, T _A	–40		85	°C

timing requirements over recommended ranges of supply voltage and operating free-air temperature

	MIN	NOM	MAX	UNIT
f _{clk} Clock frequency	0		140	MHz



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V _{IK}	Input voltage	V _{DD} = 3 V, I _I = -18 mA			-1.2	V
V _{OH}	High-level output voltage	V _{DD} = min to max, I _{OH} = -1 mA	V _{DD} -0.2			V
		V _{DD} = 3 V, I _{OH} = -24 mA	2			
		V _{DD} = 3 V, I _{OH} = -12 mA	2.4			
V _{OL}	Low-level output voltage	V _{DD} = min to max, I _{OL} = 1 mA	0.2			V
		V _{DD} = 3 V, I _{OL} = 24 mA	0.8			
		V _{DD} = 3 V, I _{OL} = 12 mA	0.55			
I _{OH}	High-level output current	V _{DD} = 3 V, V _O = 1 V	-50			mA
		V _{DD} = 3.3 V, V _O = 1.65 V	-55			
I _{OL}	Low-level output current	V _{DD} = 3 V, V _O = 2 V	60			mA
		V _{DD} = 3.3 V, V _O = 1.65 V	70			
I _I	Input current	V _I = V _O or V _{DD}			±5	μA
I _{DD}	Dynamic current, See Figure 5	f = 67 MHz			37	mA
C _i	Input capacitance	V _{DD} = 3.3 V, V _I = 0 V or V _{DD}		3		pF
C _o	Output capacitance	V _{DD} = 3.3 V, V _I = 0 V or V _{DD}		3.2		pF

† All typical values are at respective nominal V_{DD} and 25°C.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 10 pF, V_{DD} = 3.3 V ± 0.3 V (see Note 6 and Figures 1 and 2)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
t _{PLH}	High-to-low propagation delay	See Figures 1 and 2	1.8	2.5	3	ns
t _{PHL}	Low-to-high propagation delay		1.8	2.4	3	ns
t _{sk(o)}	Output skew (see Note 4)			50	100	ps
t _{sk(p)}	Pulse skew	V _{IH} = V _{DD} , V _{IL} = 0 V			150	ps
t _{sk(pr)}	Process skew			0.2	0.3	ns
t _{sk(pp)}	Part-to-part skew			0.25	0.4	ns
T _{high}	CLK high time, See Figure 4	66 MHz	6			ns
		140 MHz	3			
T _{low}	CLK low time, See Figure 4	66 MHz	6			ns
		140 MHz	3			
t _r	Output rise slew rate‡	0.2V _{DD} to 0.6V _{DD}	1.5	2.7	4	V/ns
t _f	Output fall slew rate‡	0.6V _{DD} to 0.2V _{DD}	1.5	2.7	4	V/ns

† All typical values are at respective nominal V_{DD}.

‡ This symbol is according to PCI-X terminology.

NOTE 4: The t_{sk(o)} specification is only valid for equal loading of all outputs.

PARAMETER MEASUREMENT INFORMATION

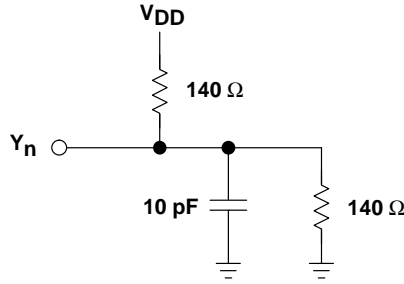


Figure 1. Test Load Circuit

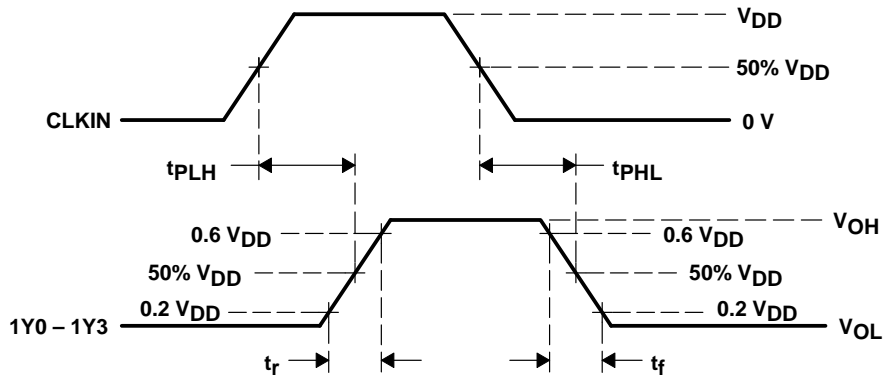


Figure 2. Voltage Thresholds for Propagation Delay (t_{pd}) Measurements

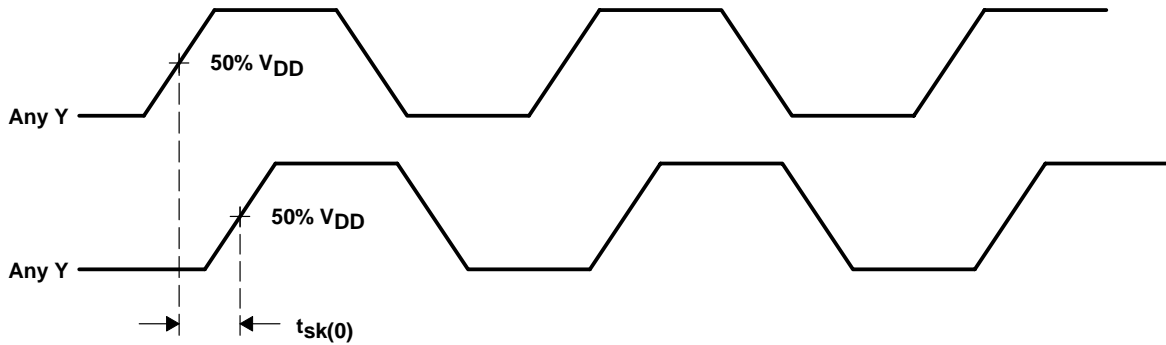
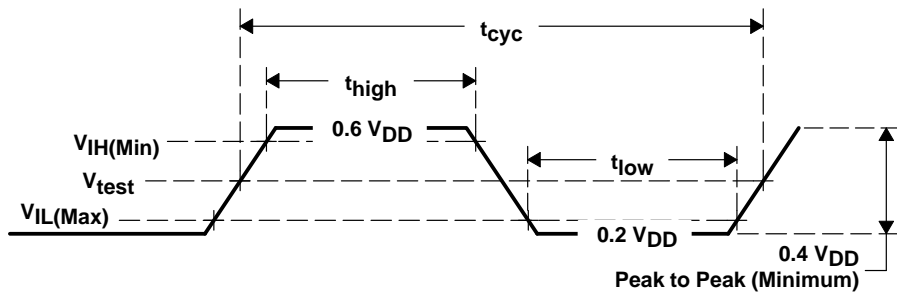


Figure 3. Output Skew

PARAMETER	VALUE	UNIT
$V_{IH}(\text{Min})$	$0.5 V_{DD}$	V
$V_{IL}(\text{Max})$	$0.35 V_{DD}$	V
V_{test}	$0.4 V_{DD}$	V



NOTE: All parameters in Figure 4 are according to PCI-X 1.0 specifications.

Figure 4. Clock Waveform

PARAMETER MEASUREMENT INFORMATION

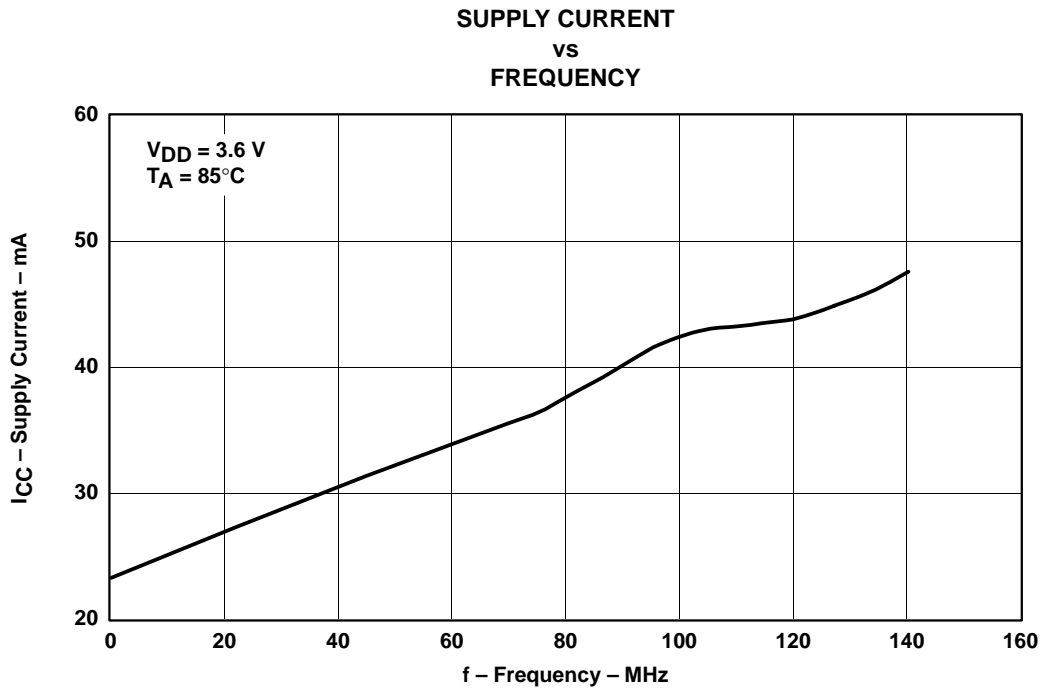


Figure 5

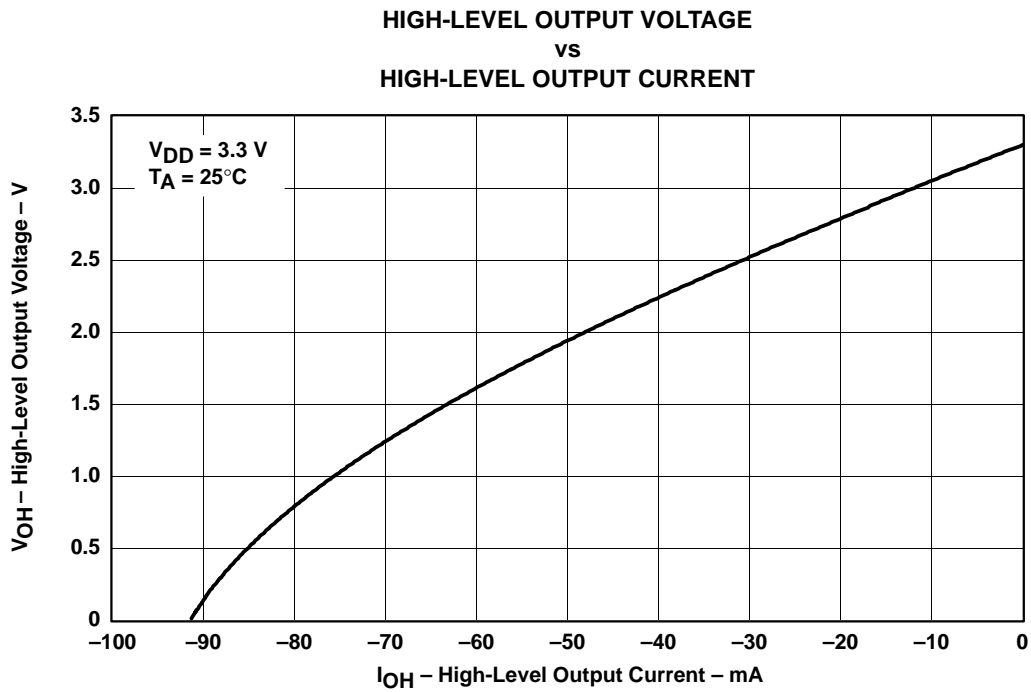


Figure 6

CDCV304 140-MHz PCI-X CLOCK BUFFER

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PARAMETER MEASUREMENT INFORMATION

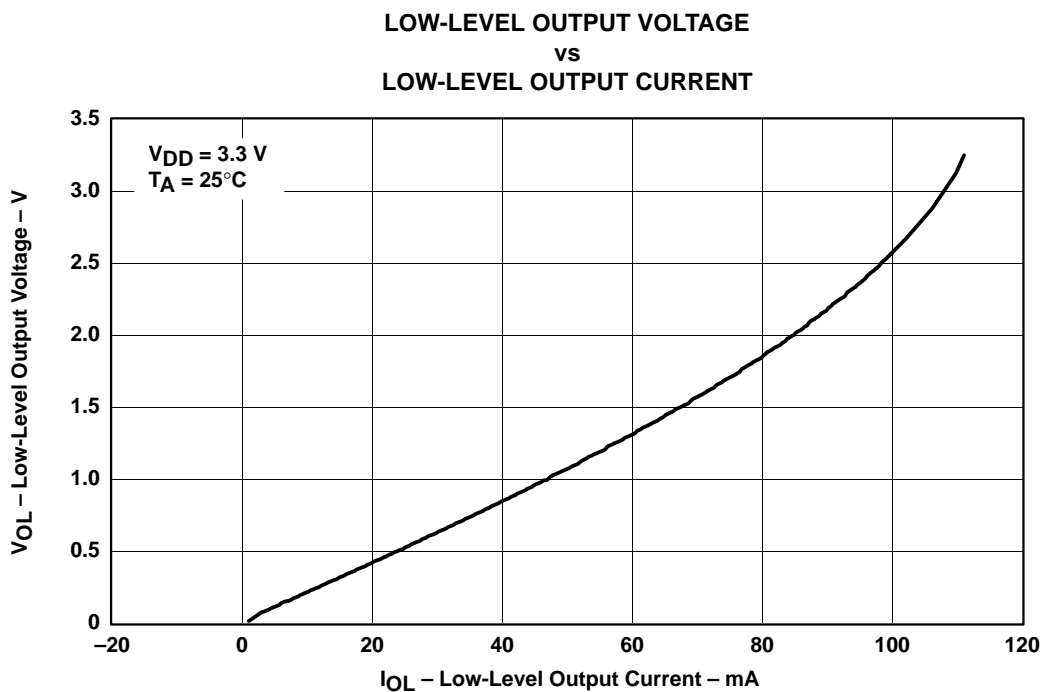


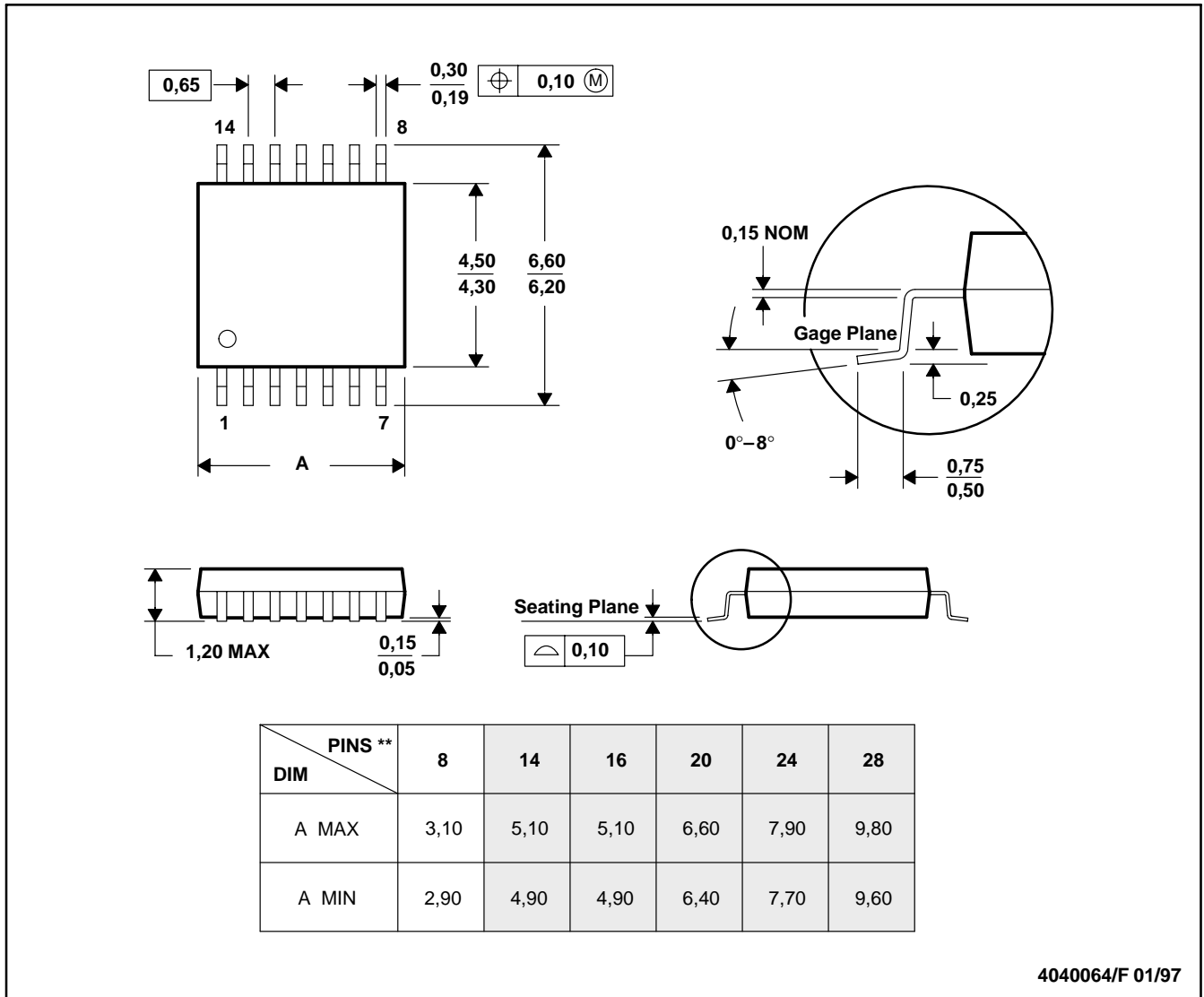
Figure 7

MECHANICAL DATA

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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Mailing Address:

Texas Instruments
Post Office Box 655303
Dallas, Texas 75265